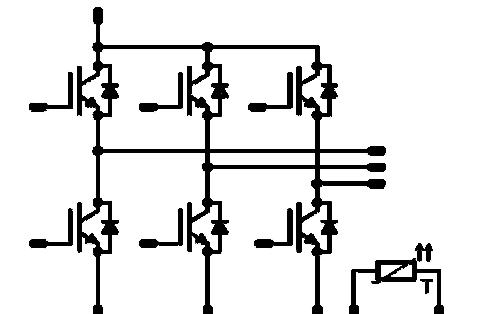


| flow90PACK 0 | | 1200V/15A |
|--|--|---|
| Features | | |
| <ul style="list-style-type: none"> • 90° PCB mounting for easy heat sink assembly • Clip-in PCB mounting (optional) • Open emitter for easy current sensing | | |
| Target Applications | | |
| <ul style="list-style-type: none"> • Standard Drive • Servo Drive • Bookshelf Inverter | | |
| Types | | |
| <ul style="list-style-type: none"> • 10-R0126PA015SC-M628F40 • 10-RZ126PA015SC-M628F41 | | |
| flow90PACK 0 | | |
| |  |  |
| | without clips | with clips |
| Schematic | | |
| |  | |

Maximum Ratings

$T_j=25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Condition | Value | Unit |
|--------------------------------------|----------------------|---|-----------|---------|
| Inverter Transistor | | | | |
| Collector-emitter break down voltage | V_{CE} | | 1200 | V |
| DC collector current * | I_C | $T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$ | 23 25 | A |
| Pulsed collector current | I_{Cpulse} | t_p limited by $T_{j\max}$ | 45 | A |
| Turn off safe operating area | | $V_{CE} \leq 1200\text{V}$, $T_j \leq T_{j\max}$ | 30 | A |
| Power dissipation per IGBT * | P_{tot} | $T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$ | 69 104 | W |
| Gate-emitter peak voltage | V_{GE} | | ±20 | V |
| Short circuit ratings | t_{sc} V_{CC} | $T_j \leq 150^\circ\text{C}$ $V_{GE}=15\text{V}$ | 10 800 | μs V |
| Maximum Junction Temperature | $T_{j\max}$ | | 175 | °C |

* measured with phase-change material

Inverter Diode

| Peak Repetitive Reverse Voltage | V_{RRM} | | 1200 | V |
|---------------------------------|-------------|---|----------|----|
| DC forward current * | I_F | $T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$ | 23 30 | A |
| Repetitive peak forward current | I_{FRM} | t_p limited by $T_{j\max}$ | 30 | A |
| Power dissipation per Diode * | P_{tot} | $T_j=T_{j\max}$ $T_h=80^\circ\text{C}$ $T_c=80^\circ\text{C}$ | 53 81 | W |
| Maximum Junction Temperature | $T_{j\max}$ | | 175 | °C |

* measured with phase-change material

Maximum Ratings

T_j=25°C, unless otherwise specified

| Parameter | Symbol | Condition | Value | Unit |
|-----------|--------|-----------|-------|------|
|-----------|--------|-----------|-------|------|

Thermal Properties

| | | | | |
|---|------------------|--|---------------------------------|----|
| Storage temperature | T _{stg} | | -40...+125 | °C |
| Operation temperature under switching condition | T _{op} | | -40...+(T _{jmax} - 25) | °C |

Insulation Properties

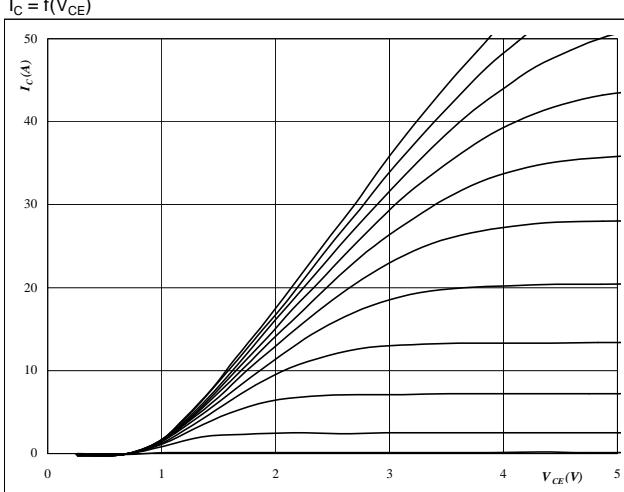
| | | | | | |
|----------------------------|-----------------|------|------------|-----------|----|
| Insulation voltage | V _{is} | t=2s | DC voltage | 4000 | V |
| Creepage distance | | | | min 12,7 | mm |
| Clearance | | | | min 10,93 | mm |
| Comparative tracking index | CTI | | | >200 | |

Characteristic Values

| Parameter | Symbol | Conditions | | | | | Value | | | Unit |
|---|---------------------------------------|--|---------------------------------|---|---|---|--------------|--------------|------|------------------------|
| | | | V_{GE} [V] or V_{GS} [V] | V_r [V] or V_{CE} [V] or V_{DS} [V] | I_c [A] or I_F [A] or I_D [A] | T_j | Min | Typ | Max | |
| Inverter Transistor | | | | | | | | | | |
| Gate emitter threshold voltage | $V_{GE(th)}$ | $V_{CE}=V_{GE}$ | | | 0,0005 | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 5 | 5,8 | 6,5 | V |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | | 15 | | 15 | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 1,5 | 1,93 2,23 | 2,3 | V |
| Collector-emitter cut-off current incl. Diode | I_{CES} | | 0 | 1200 | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | | | 0,01 | mA |
| Gate-emitter leakage current | I_{GES} | | 20 | 0 | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | | | 200 | nA |
| Integrated Gate resistor | R_{gint} | | | | | | | none | | Ω |
| Turn-on delay time | $t_{d(on)}$ | $R_{goff}=32\ \Omega$ $R_{gon}=32\ \Omega$ | ± 15 | 600 | 15 | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 86 85 | | | ns |
| Rise time | t_r | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 34 35 | | | |
| Turn-off delay time | $t_{d(off)}$ | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 202 272 | | | |
| Fall time | t_f | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 70 124 | | | |
| Turn-on energy loss per pulse | E_{on} | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 1,18 1,76 | | | mWs |
| Turn-off energy loss per pulse | E_{off} | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 0,81 1,39 | | | |
| Input capacitance | C_{ies} | $f=1\text{MHz}$ | 0 | 25 | | $T_j=25^\circ\text{C}$ | 900 | | | pF |
| Output capacitance | C_{oss} | | | | | | 80 | | | |
| Reverse transfer capacitance | C_{rss} | | | | | | 55 | | | |
| Gate charge | Q_{Gate} | | 15 | 960 | 15 | $T_j=25^\circ\text{C}$ | | 85 | | nC |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Phase-Change Material | | | | | | 1,38 | | K/W |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Thermal grease thickness≤50μm $\lambda = 1\text{ W/mK}$ | | | | | | 1,63 | | K/W |
| Inverter Diode | | | | | | | | | | |
| Diode forward voltage | V_F | | | | 15 | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 1,2 | 1,86 1,78 | 2,3 | V |
| Peak reverse recovery current | I_{RRM} | $R_{gon}=32\ \Omega$ | ± 15 | 600 | 15 | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 10 13 | | | A |
| Reverse recovery time | t_{rr} | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 297 508 | | | ns |
| Reverse recovered charge | Q_{rr} | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 1,46 2,94 | | | μC |
| Peak rate of fall of recovery current | $\frac{di(\text{rec})}{dt}\text{max}$ | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 58 45 | | | $\text{A}/\mu\text{s}$ |
| Reverse recovered energy | E_{rec} | | | | | $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$ | 0,57 1,18 | | | mWs |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Phase-Change Material | | | | | | 1,78 | | K/W |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Thermal grease thickness≤50μm $\lambda = 1\text{ W/mK}$ | | | | | | 2,09 | | K/W |
| Thermistor | | | | | | | | | | |
| Rated resistance | R | | | | | $T_j=25^\circ\text{C}$ | | 4700 | | Ω |
| Deviation of R25 | $\Delta R/R$ | | | | | $T_j=25^\circ\text{C}$ | -5 | | 5 | % |
| Power dissipation | P | | | | | $T_j=25^\circ\text{C}$ | | 200 | | mW |
| Power dissipation constant | | | | | | $T_j=25^\circ\text{C}$ | | 2 | | mW/K |
| B-value | $B_{(25/50)}$ | Tol. ±3% | | | | $T_j=25^\circ\text{C}$ | | 3500 | | K |
| B-value | $B_{(25/100)}$ | | | | | $T_j=25^\circ\text{C}$ | | 3560 | | K |
| Vincotech NTC Reference | | | | | | | | | G | |

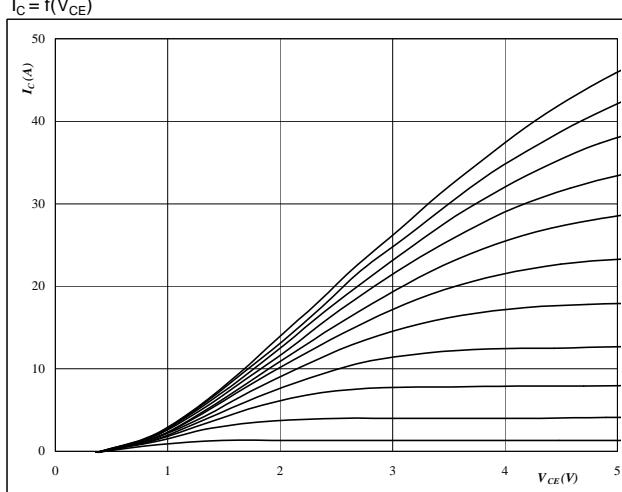
Output Inverter

Figure 1
Typical output characteristics
 $I_C = f(V_{CE})$



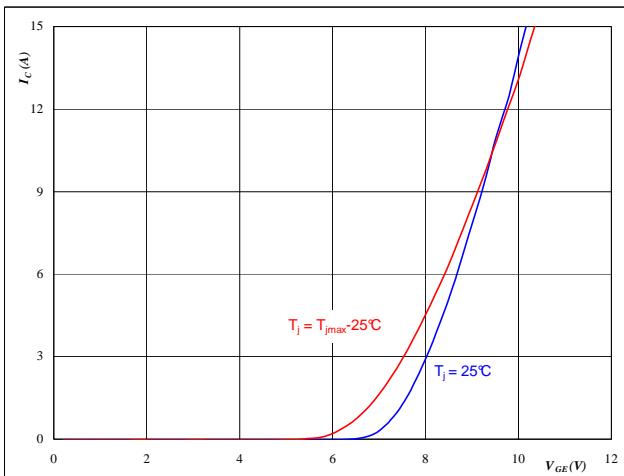
At
 $t_p = 250 \mu s$
 $T_j = 25^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2
Typical output characteristics
 $I_C = f(V_{CE})$



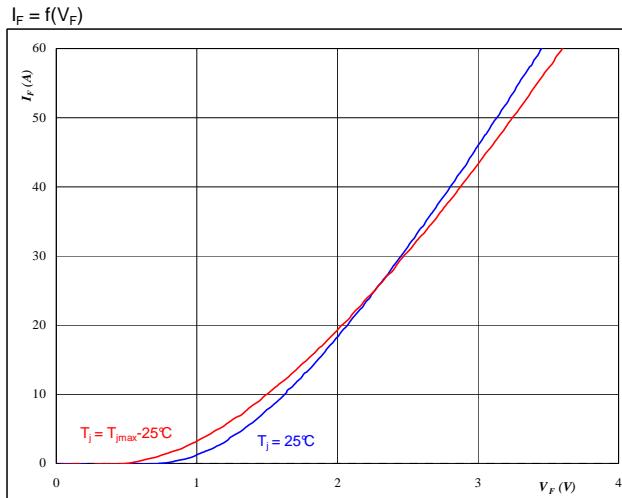
At
 $t_p = 250 \mu s$
 $T_j = 150^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3
Typical transfer characteristics
 $I_C = f(V_{GE})$



At
 $t_p = 250 \mu s$
 $V_{CE} = 10 V$

Figure 4
Typical diode forward current as a function of forward voltage
 $I_F = f(V_F)$



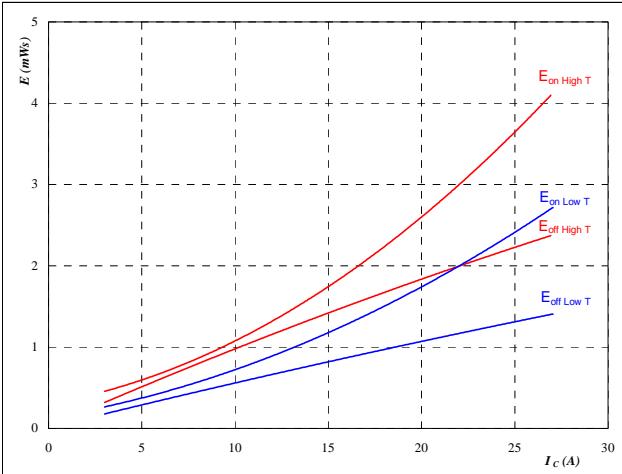
At
 $t_p = 250 \mu s$

Output Inverter

Figure 5

Typical switching energy losses
as a function of collector current

$$E = f(I_C)$$



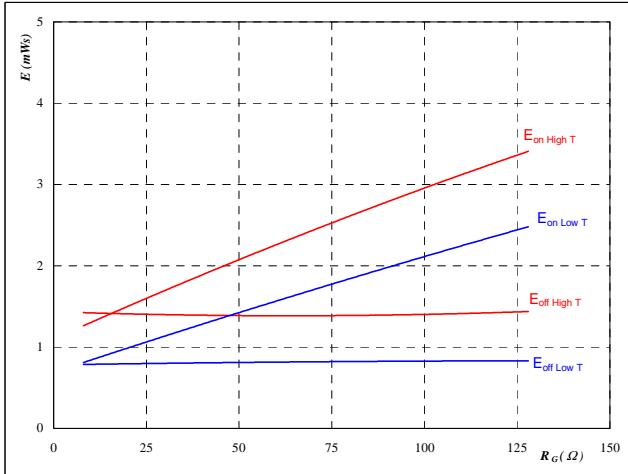
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 32 \quad \Omega \\ R_{goff} &= 32 \quad \Omega \end{aligned}$$

Output inverter IGBT
Figure 6

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



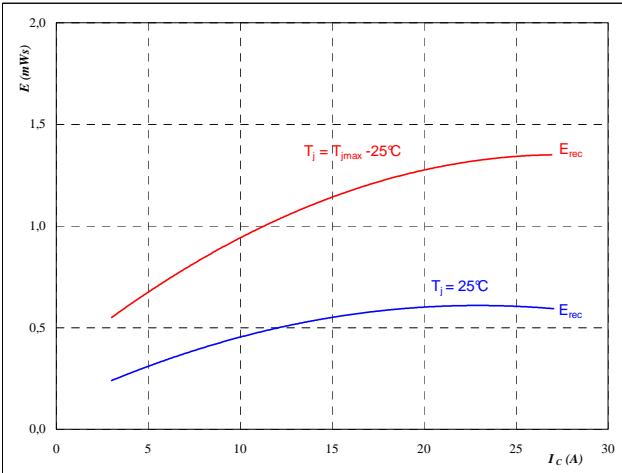
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ I_C &= 15 \quad \text{A} \end{aligned}$$

Figure 7
Output inverter FWD

Typical reverse recovery energy loss
as a function of collector current

$$E_{rec} = f(I_C)$$



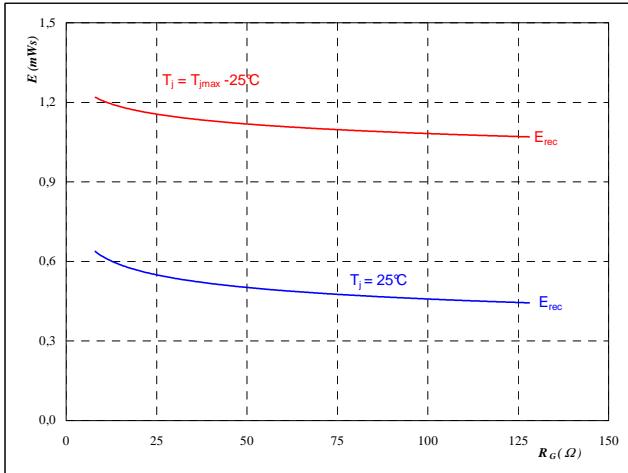
With an inductive load at

$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 32 \quad \Omega \end{aligned}$$

Figure 8
Output inverter FWD

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

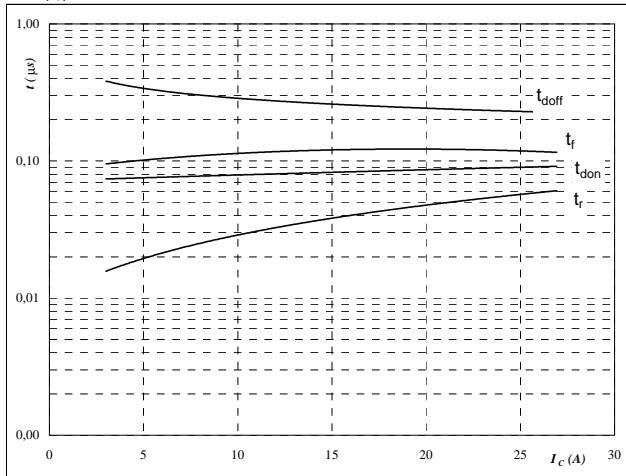
$$\begin{aligned} T_j &= 25/150 \quad ^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ I_C &= 15 \quad \text{A} \end{aligned}$$

Output Inverter

Figure 9

Typical switching times as a function of collector current

$$t = f(I_C)$$



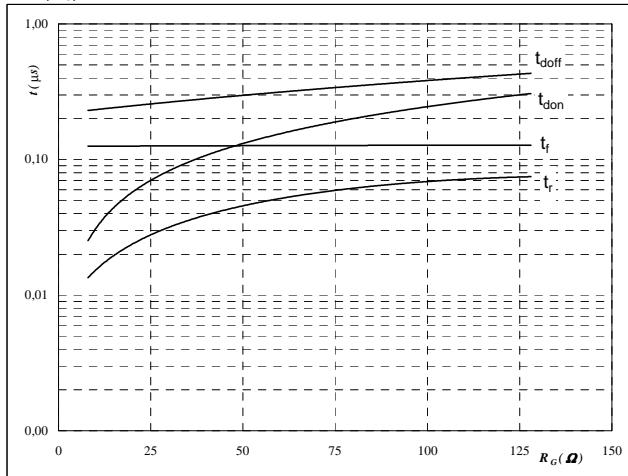
With an inductive load at

| | | |
|---------------------|-----|----|
| T _j = | 150 | °C |
| V _{CE} = | 600 | V |
| V _{GE} = | ±15 | V |
| R _{gon} = | 32 | Ω |
| R _{goff} = | 32 | Ω |

Figure 10

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



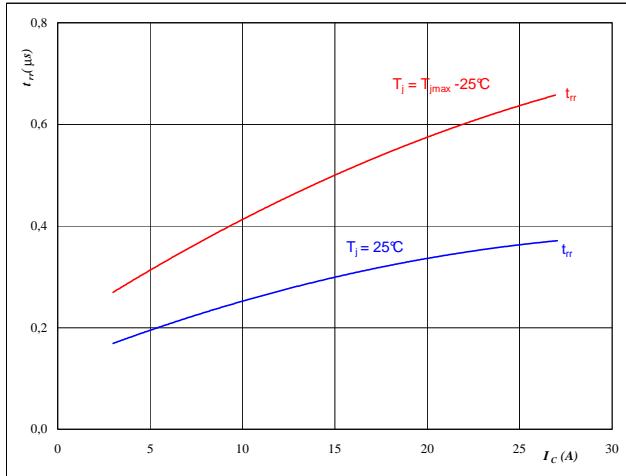
With an inductive load at

| | | |
|-------------------|-----|----|
| T _j = | 150 | °C |
| V _{CE} = | 600 | V |
| V _{GE} = | ±15 | V |
| I _C = | 15 | A |

Figure 11
Output inverter FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_C)$$



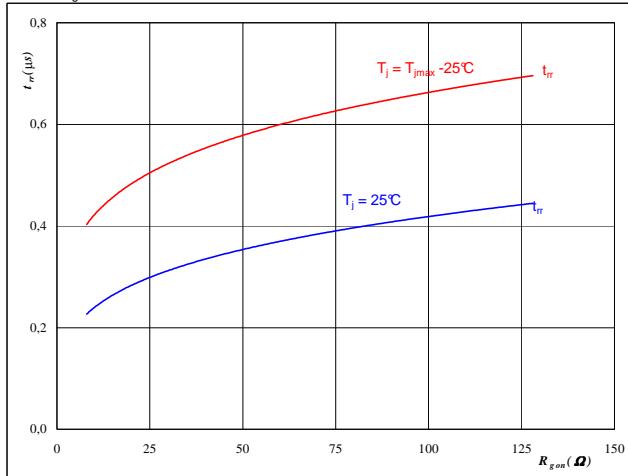
At

| | | |
|--------------------|--------|----|
| T _j = | 25/150 | °C |
| V _{CE} = | 600 | V |
| V _{GE} = | ±15 | V |
| R _{gon} = | 32 | Ω |

Figure 12
Output inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



At

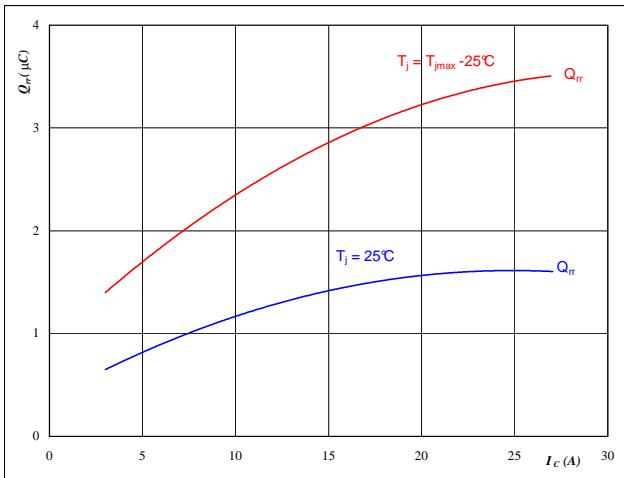
| | | |
|-------------------|--------|----|
| T _j = | 25/150 | °C |
| V _R = | 600 | V |
| I _F = | 15 | A |
| V _{GE} = | ±15 | V |

Output Inverter

Figure 13

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$

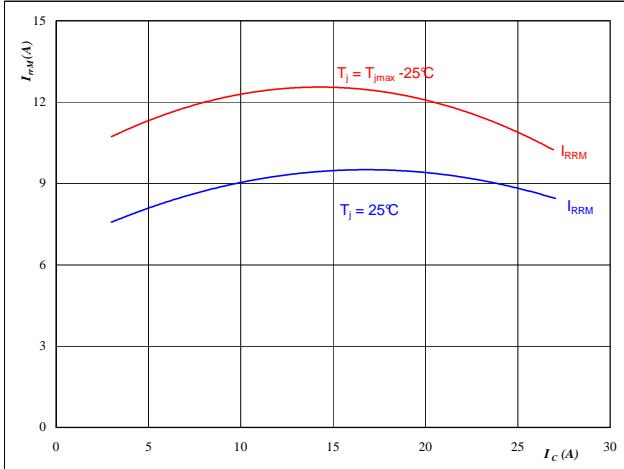

At

$$\begin{aligned} T_j &= 25/150 \quad {}^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 32 \quad \Omega \end{aligned}$$

Figure 15

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$

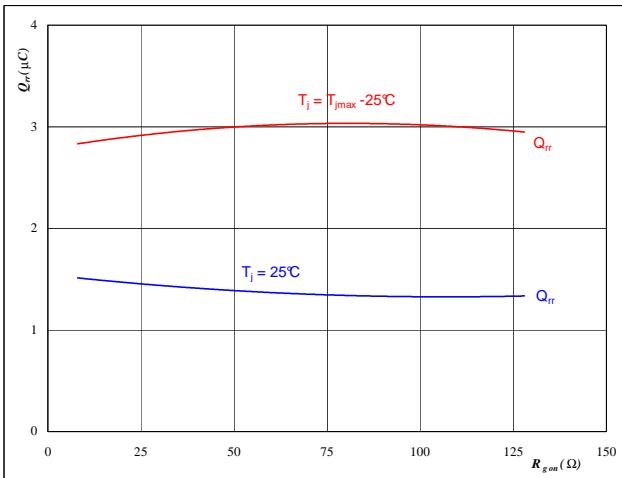

At

$$\begin{aligned} T_j &= 25/150 \quad {}^\circ\text{C} \\ V_{CE} &= 600 \quad \text{V} \\ V_{GE} &= \pm 15 \quad \text{V} \\ R_{gon} &= 32 \quad \Omega \end{aligned}$$

Figure 14

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$

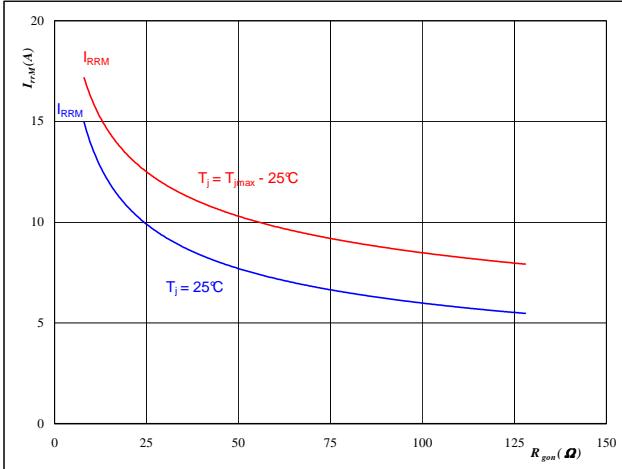

At

$$\begin{aligned} T_j &= 25/150 \quad {}^\circ\text{C} \\ V_R &= 600 \quad \text{V} \\ I_F &= 15 \quad \text{A} \\ V_{GE} &= \pm 15 \quad \text{V} \end{aligned}$$

Figure 16

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$

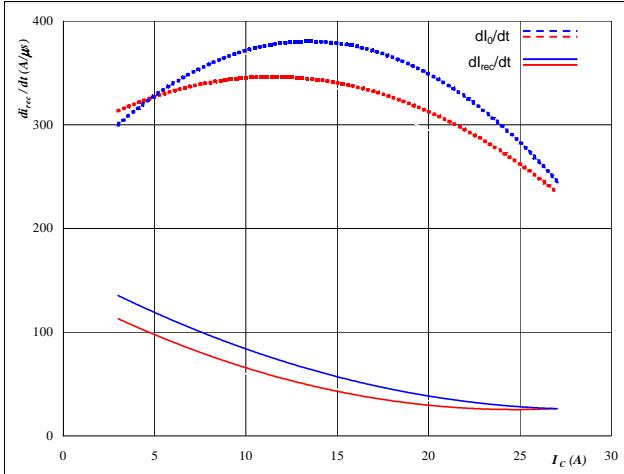

At

$$\begin{aligned} T_j &= 25/150 \quad {}^\circ\text{C} \\ V_R &= 600 \quad \text{V} \\ I_F &= 15 \quad \text{A} \\ V_{GE} &= \pm 15 \quad \text{V} \end{aligned}$$

Output Inverter

Figure 17

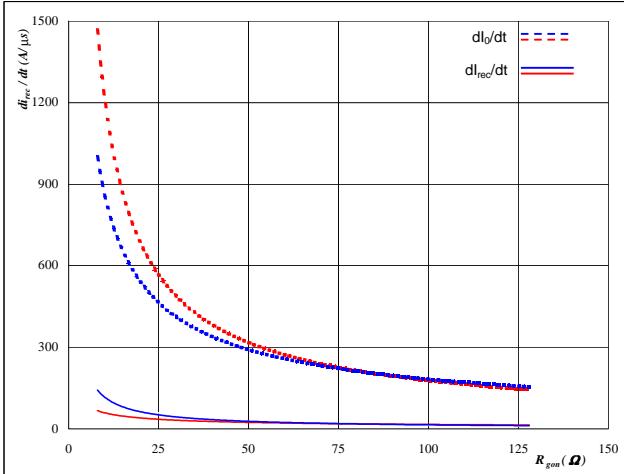
Typical rate of fall of forward
and reverse recovery current as a
function of collector current
 $dl_0/dt, dl_{rec}/dt = f(I_C)$


At

$T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 32 \Omega$

Output inverter FWD
Figure 18

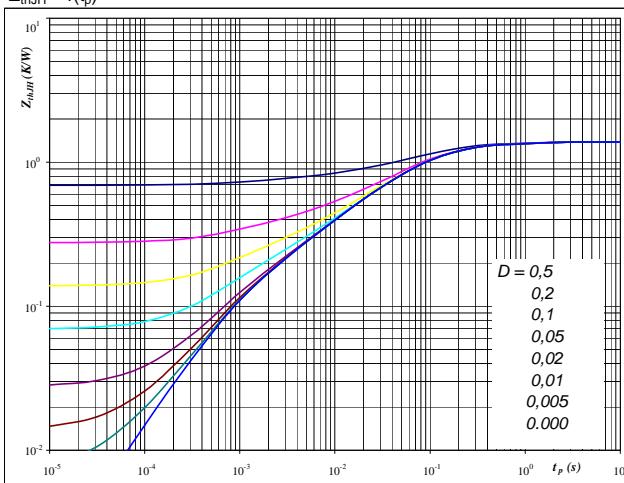
Typical rate of fall of forward
and reverse recovery current as a
function of IGBT turn on gate resistor
 $dl_0/dt, dl_{rec}/dt = f(R_{gon})$


At

$T_j = 25/150 \text{ } ^\circ\text{C}$
 $V_R = 600 \text{ V}$
 $I_F = 15 \text{ A}$
 $V_{GE} = \pm 15 \text{ V}$

Figure 19
Output inverter IGBT

IGBT transient thermal impedance
as a function of pulse width
 $Z_{thJH} = f(t_p)$


At

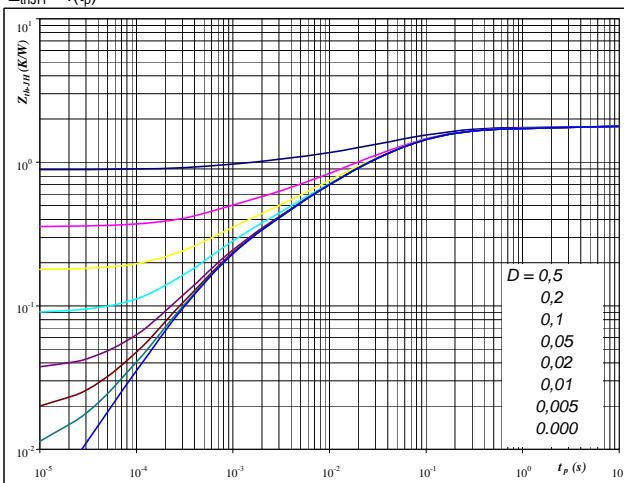
$D = t_p / T$
 $R_{thJH} = 1,38 \text{ K/W}$ $R_{thJH} = 1,63 \text{ K/W}$

IGBT thermal model values

| Phase change interface | | Thermal grease | |
|------------------------|---------|----------------|---------|
| R (C/W) | Tau (s) | R (C/W) | Tau (s) |
| 0,14 | 7,1E-01 | 0,16 | 7,1E-01 |
| 0,55 | 1,0E-01 | 0,65 | 1,0E-01 |
| 0,40 | 3,6E-02 | 0,47 | 3,6E-02 |
| 0,19 | 7,0E-03 | 0,22 | 7,0E-03 |
| 0,10 | 9,2E-04 | 0,12 | 9,2E-04 |

Figure 20
Output inverter FWD

FWD transient thermal impedance
as a function of pulse width
 $Z_{thJH} = f(t_p)$


At

$D = t_p / T$
 $R_{thJH} = 1,78 \text{ K/W}$ $R_{thJH} = 2,09 \text{ K/W}$

FWD thermal model values

| Phase change interface | | Thermal grease | |
|------------------------|---------|----------------|---------|
| R (C/W) | Tau (s) | R (C/W) | Tau (s) |
| 0,07 | 2,6E+00 | 0,08 | 2,6E+00 |
| 0,12 | 3,9E-01 | 0,15 | 3,9E-01 |
| 0,72 | 6,9E-02 | 0,84 | 6,9E-02 |
| 0,45 | 1,7E-02 | 0,53 | 1,7E-02 |
| 0,24 | 3,8E-03 | 0,29 | 3,8E-03 |
| 0,18 | 6,4E-04 | 0,21 | 6,4E-04 |

Output Inverter

Figure 21

Power dissipation as a function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

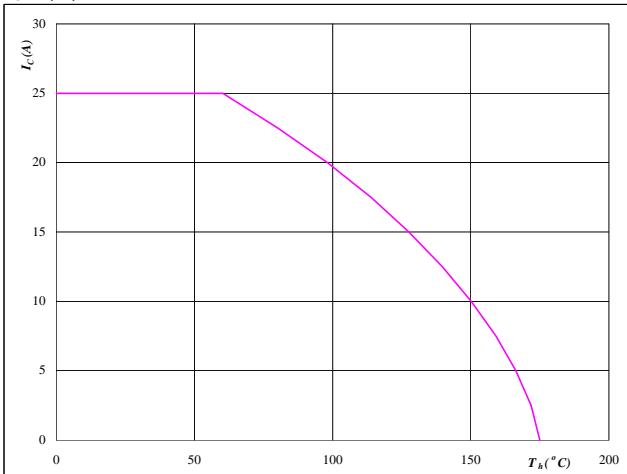

At

$$T_j = 175 \quad ^\circ\text{C}$$

Output inverter IGBT
Figure 22

Collector current as a function of heatsink temperature

$$I_C = f(T_h)$$

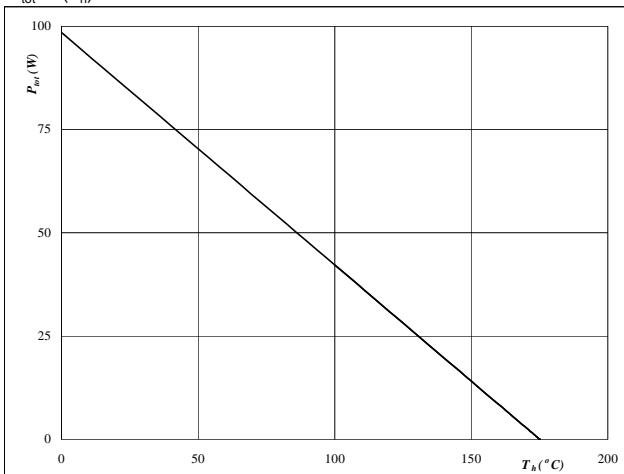

At

$$T_j = 175 \quad ^\circ\text{C}$$

Output inverter IGBT
Figure 23
Output inverter FWD

Power dissipation as a function of heatsink temperature

$$P_{\text{tot}} = f(T_h)$$

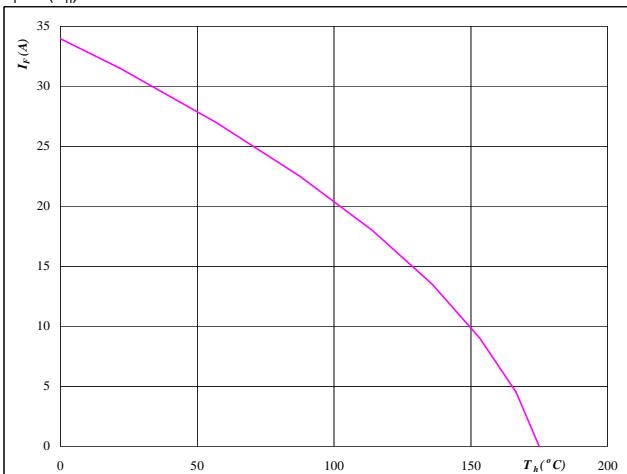

At

$$T_j = 175 \quad ^\circ\text{C}$$

Figure 24
Output inverter FWD

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$


At

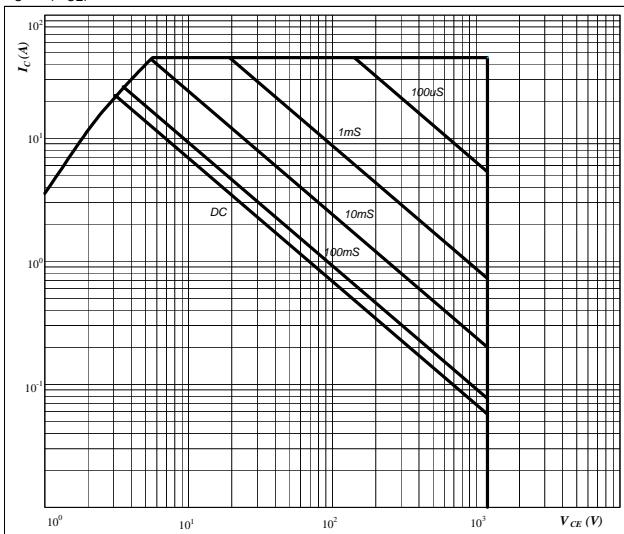
$$T_j = 175 \quad ^\circ\text{C}$$

Output Inverter

Figure 25

Safe operating area as a function of collector-emitter voltage

$$I_C = f(V_{CE})$$


At

D = single pulse

T_h = 80 °C

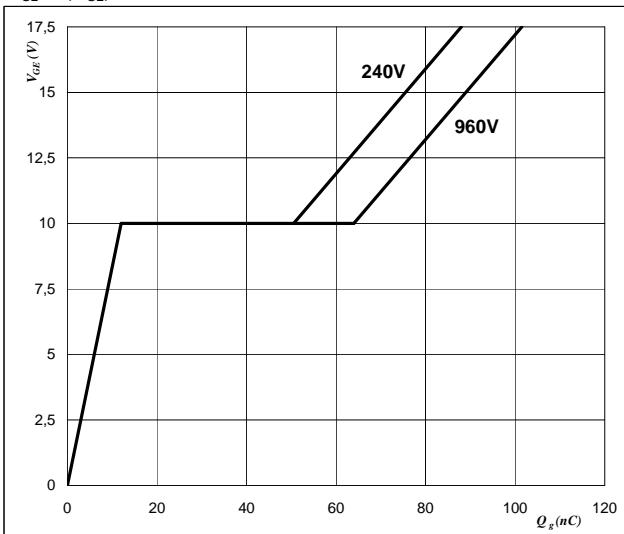
V_{GE} = ±15 V

T_j = T_{jmax} °C

Output inverter IGBT
Figure 26

Gate voltage vs Gate charge

$$V_{GE} = f(Q_{GE})$$

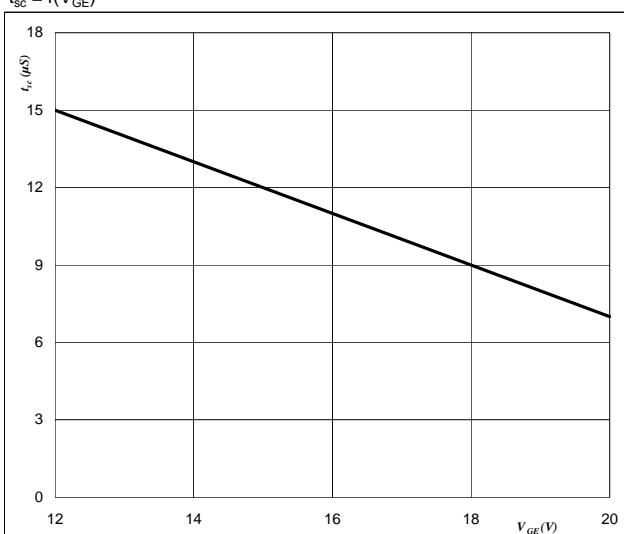

At

I_C = 15 A

Figure 27
Output inverter IGBT

Short circuit withstand time as a function of gate-emitter voltage

$$t_{sc} = f(V_{GE})$$


At

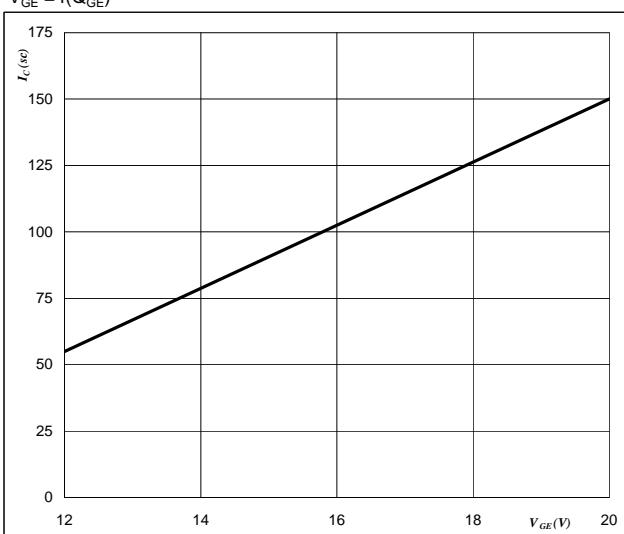
V_{CE} = 1200 V

T_j ≤ 175 °C

Figure 28
Output inverter IGBT

Typical short circuit collector current as a function of gate-emitter voltage

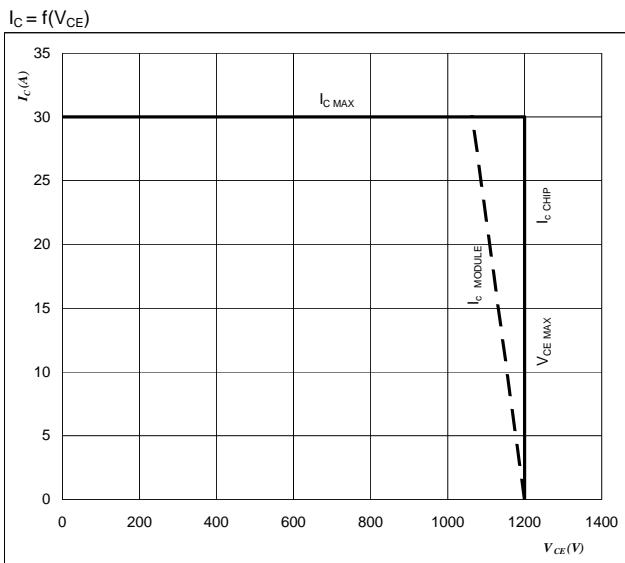
$$V_{GE} = f(Q_{GE})$$


At

V_{CE} ≤ 600 V

T_j = 175 °C

Figure 29
Reverse bias safe operating area



At

$$T_j = T_{j\max} - 25 \quad ^\circ\text{C}$$

$$U_{ccminus} = U_{ccplus}$$

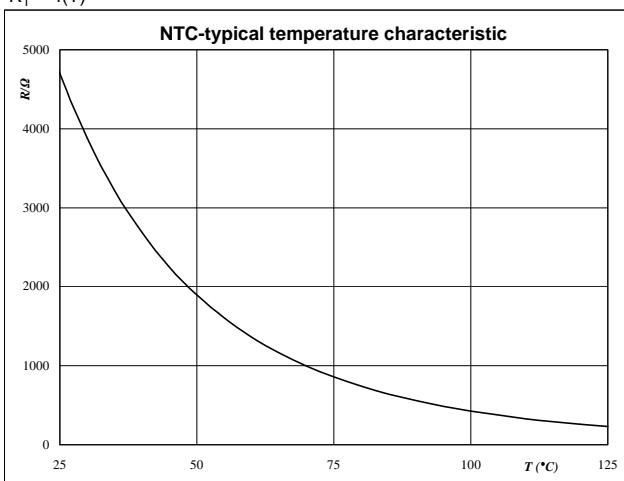
Switching mode : 3 level switching

Thermistor

Figure 1 Thermistor

Typical NTC characteristic
as a function of temperature

$$R_T = f(T)$$



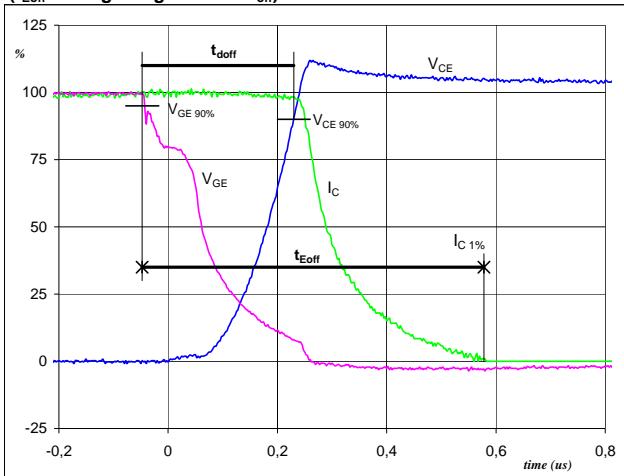
Switching Definitions Output Inverter

General conditions

| | | |
|------------|---|--------|
| T_j | = | 150 °C |
| R_{gon} | = | 32 Ω |
| R_{goff} | = | 32 Ω |

Figure 1

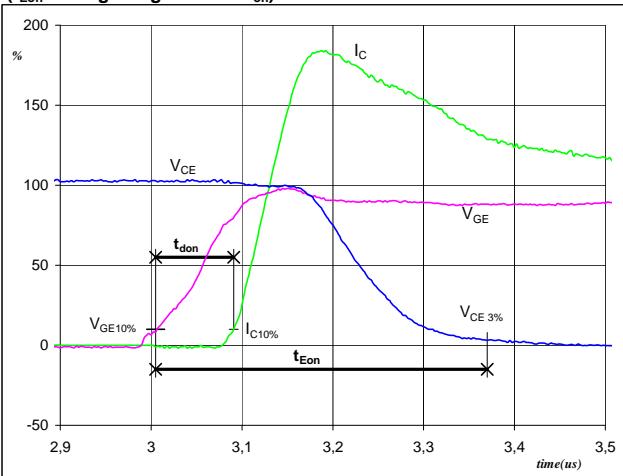
Output inverter IGBT
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
(t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%) = -15$ V
 $V_{GE}(100\%) = 15$ V
 $V_C(100\%) = 600$ V
 $I_C(100\%) = 15$ A
 $t_{doff} = 0,27$ μs
 $t_{Eoff} = 0,63$ μs

Figure 2

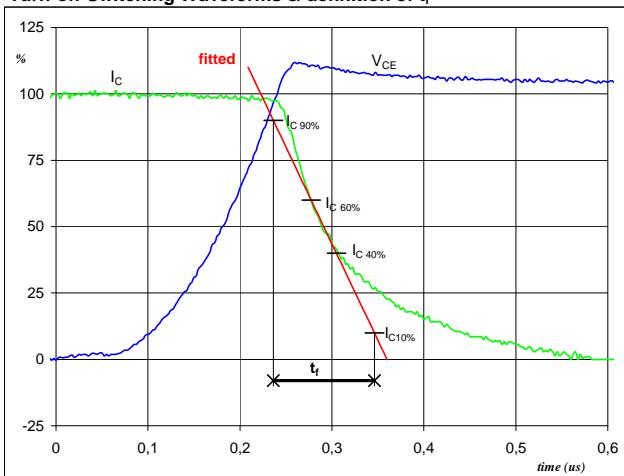
Output inverter IGBT
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
(t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%) = -15$ V
 $V_{GE}(100\%) = 15$ V
 $V_C(100\%) = 600$ V
 $I_C(100\%) = 15$ A
 $t_{don} = 0,09$ μs
 $t_{Eon} = 0,36$ μs

Figure 3

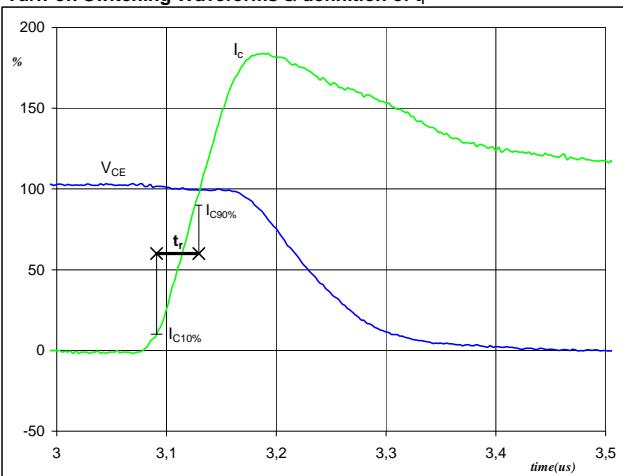
Output inverter IGBT
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%) = 600$ V
 $I_C(100\%) = 15$ A
 $t_f = 0,12$ μs

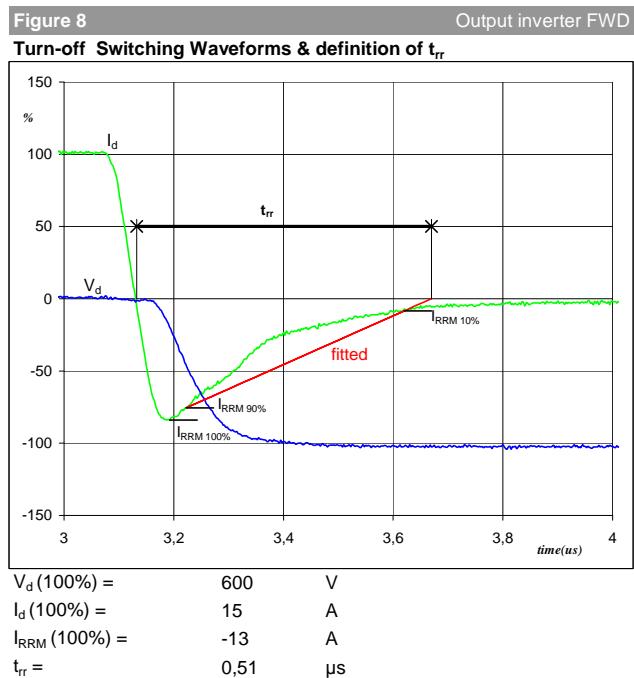
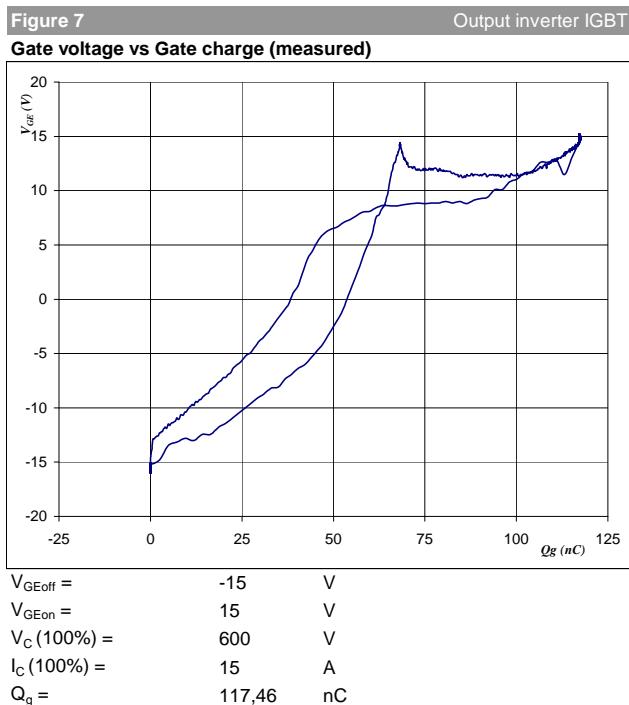
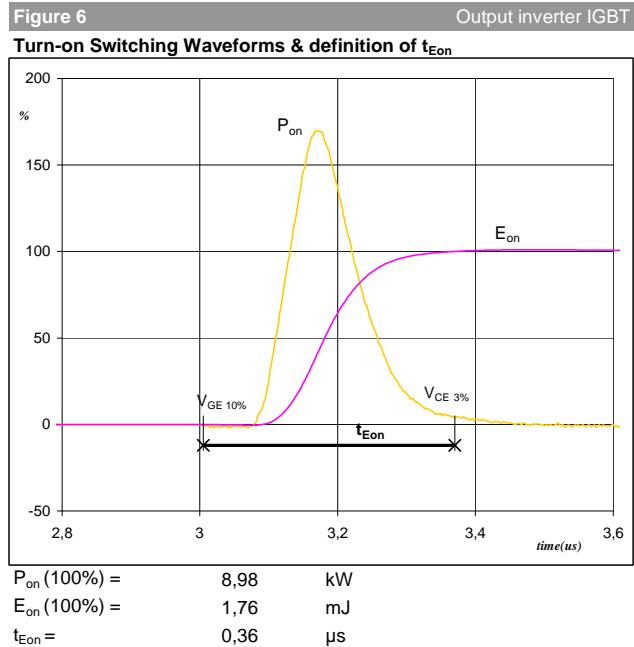
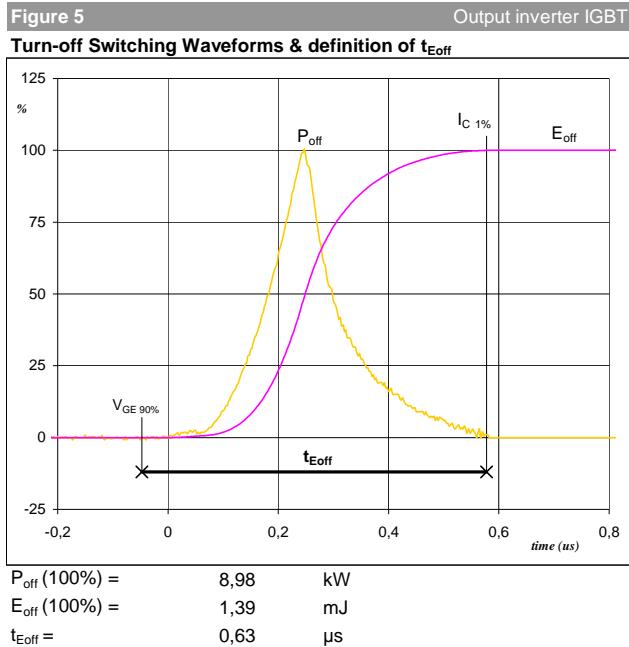
Figure 4

Output inverter IGBT
Turn-on Switching Waveforms & definition of t_r



$V_C(100\%) = 600$ V
 $I_C(100\%) = 15$ A
 $t_r = 0,04$ μs

Switching Definitions Output Inverter

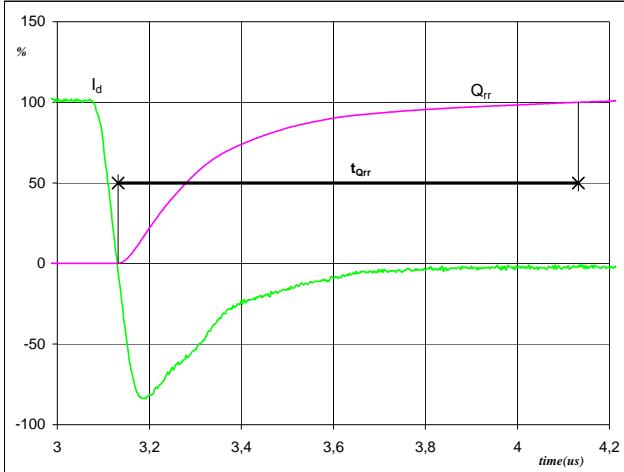


Switching Definitions Output Inverter

Figure 9

Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Qrr}
 $(t_{Qrr} = \text{integrating time for } Q_{rr})$

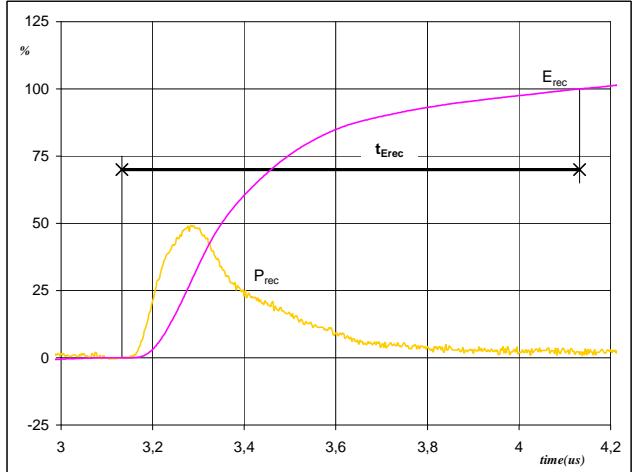


$I_d(100\%) = 15 \text{ A}$
 $Q_{rr}(100\%) = 2,94 \mu\text{C}$
 $t_{Qrr} = 1,00 \mu\text{s}$

Figure 10

Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Erec}
 $(t_{Erec} = \text{integrating time for } E_{rec})$



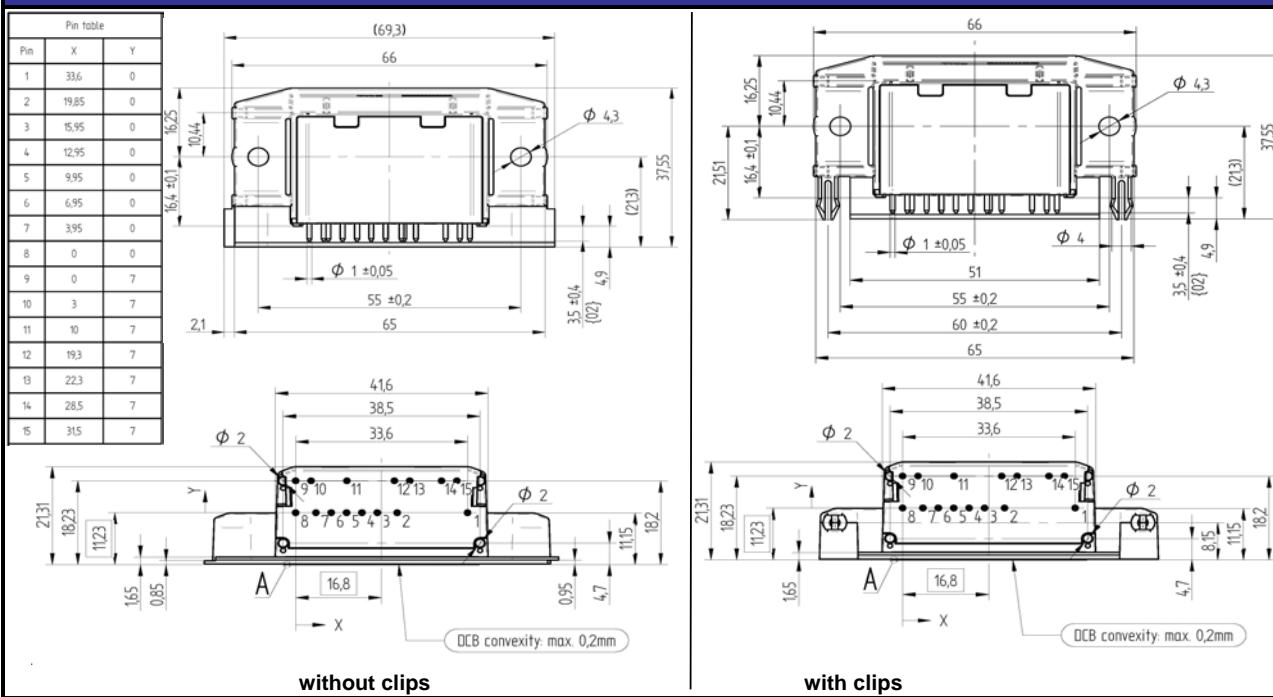
$E_{rec}(100\%) = 8,98 \text{ kW}$
 $P_{rec}(100\%) = 1,18 \text{ mJ}$
 $t_{Erec} = 1,00 \mu\text{s}$

Ordering Code and Marking - Outline - Pinout

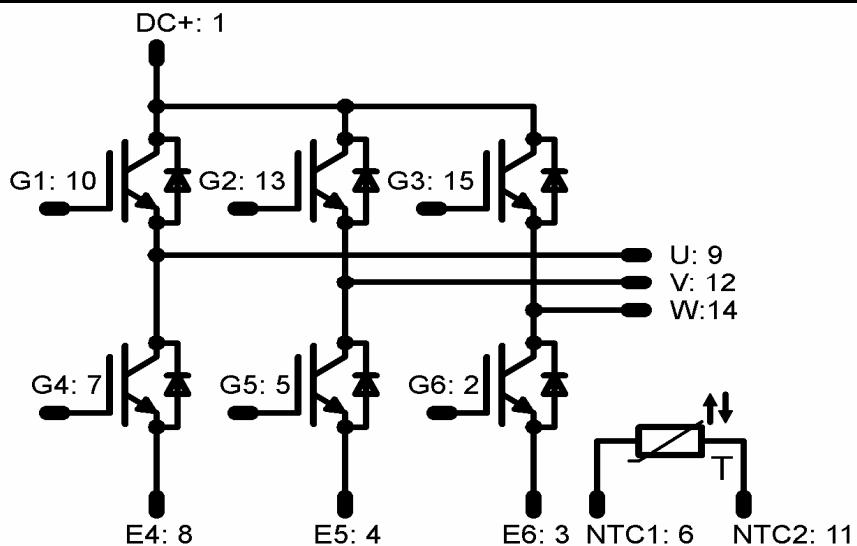
Ordering Code & Marking

| Version | Ordering Code | in DataMatrix as | in packaging barcode as |
|--|-------------------------|------------------|-------------------------|
| without thermal paste ,housing without clips | 10-RZ126PA015SC-M628F41 | M628F41 | M628F41 |
| without thermal paste ,housing with clips | 10-R0126PA015SC-M628F40 | M628F40 | M628F40 |

Outline



Pinout



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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.